



Title of Change:	Conversion to XDLF Lead frame for 14L & 16L SOIC products assembled at Amkor Technology Philippines P1. Mold compound will also be changed.																																	
Proposed first ship date:	21 June 2016 <i>or earlier upon customer approval</i>																																	
Contact information:	Contact your local ON Semiconductor Sales Office or < Sunitha.Kundurti@onsemi.com>																																	
Samples:	Contact your local ON Semiconductor Sales Office or < Sunitha.Kundurti@onsemi.com>																																	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Phine.Guevarra@onsemi.com>																																	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.																																	
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____																																	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____																																	
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s) Amkor Technology Philippines P1																																	
Description and Purpose:																																		
Lead frame format change from HDLF (High density Lead frame) to XDLF (Extreme Density Lead Frame) for 14L & 16L SOIC products assembled in Amkor Technology Philippines P1. This change in lead frame format also requires a change in mold material pellet size.																																		
Summarize on the table below are the packages for transfer and its equivalent bill of materials:																																		
<table border="1"> <thead> <tr> <th>Item of change</th> <th>Before</th> <th>After</th> <th>Remarks</th> </tr> </thead> <tbody> <tr> <td>Supplier</td> <td>PSMP</td> <td>ASM</td> <td>Changed</td> </tr> <tr> <td>Lead frame format(Length x width)</td> <td>HDLF(250X70MM)</td> <td>XDLF (300X100MM)</td> <td>Changed</td> </tr> <tr> <td>Mold compound</td> <td>G600(14*5.2)</td> <td>G600(18*20)</td> <td>Changed</td> </tr> </tbody> </table>					Item of change	Before	After	Remarks	Supplier	PSMP	ASM	Changed	Lead frame format(Length x width)	HDLF(250X70MM)	XDLF (300X100MM)	Changed	Mold compound	G600(14*5.2)	G600(18*20)	Changed														
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Reliability Data Summary:																																		
The qualification is performed per type of package.																																		
The principle of similarity will be applied: 1 qualification on 1 representative product will serve for all products qualified.																																		
QV DEVICE NAME: FS7140-01G-XTD																																		
PACKAGE : SOIC																																		
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**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
FS6370-01G-XTD	FS7140-01G-XTD
FS7140-01G-XTD	FS7140-01G-XTD
FS7140-01G-XTP	FS7140-01G-XTD
FS6377-01G-XTP	FS7140-01G-XTD
FS6377-01G-XTD	FS7140-01G-XTD